IPC ASSOCIATION CONNE	© Copyright 2005. IPC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both This clevel	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and Mfc Information			
Supplier Info	rmation													
Company name*			Company unique ID			Un	Unique ID Authority				Response Date*			
nsemi											2023-06-08			
Contact Name		·	Title - Contact			Ph	Phone - Contact*				Email - Contact*			
Product-Env-St	ewards		Product Enviro Compliance			N/	NA				Product-Env-Stewards@onsemi.com			
uthorized Rep	resentative*	Title - Representative			Ph	Phone - Representative*				Email - Representative*				
Product-Env-St	ewards	Product Enviro Compliance			N/	NA				Product-Env-Stewards@onsemi.com				
Requ	ester Item Number	m Number Mfr Item Number Mfr Item Name  NLAS3899BMNTWG Dual DPDT Low I Switch		Mfr Item Name		E	ffective Date	Version	M	Manufacturing Site		Weight*	UOM	Unit Type
				Dual DPDT Low Ro Switch	ON, Low Capacitan	nce 20	023-06-08	08 MY1			26.42	mg	Each	
Ianufacturii	ng Proccess Informatio	on												
Terminal Plating / Grid Array Material Terminal Base Alloy			Alloy J-S	STD-020 MSL Ratii	ng	Peak Proces	ss Body Tem	perature	Max Time at Peak	Tempera	ure Numb	er of Reflow Cyc	cles	
Matte Tin (Sn) - annealed CU			CU Alloy 1				260 C 30			seconds 3				
omments														
vel 1 - maximu	m time at peak temperature	e during sol	dering is 10-3	0 seconds										
or more inform	nation regarding material co	omposition p	please refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.28	mg	Supplier Silicon (Si)		7440-21-3		1.28	mg
Die Attach	0.22	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.044	mg
			Supplier	Silver (Ag)	7440-22-4		0.176	mg
Lead Frame	10.18	mg	Supplier	Silver (Ag)	7440-22-4		0.1527	mg
			Supplier	Tin (Sn)	7440-31-5		0.0255	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0224	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0255	mg
			Supplier	Copper (Cu)	7440-50-8		9.954	mg
Mold Compound-Black	14.24			Epoxy resin	proprietary data		0.6693	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.424	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0142	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		11.4632	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.6693	mg
Plating	0.36	mg	Supplier	Tin (Sn)	7440-31-5		0.36	mg
Wire Bond - Au	0.14	mg	Supplier	Gold (Au)	7440-57-5		0.14	mg